



## Advance Product Change Notification

201611012A

**Issue Date:** 09-Dec-2016

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# QUALITY

### Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input checked="" type="checkbox"/> Electrical spec./Test coverage

Change ssMOS wafer supplier; in SOT23 change bond wire, mold compound and leadframe

### Details of this Planned Change

Scheduled changes affect ssMOSFET types PMV130ENEA, PMV130ENEA/DG/B2 in package SOT23 and PMXB360ENEA in package DFN1010D-3 (SOT1215).

The products made using the T6 TrenchMOS silicon process sourced from Global Foundries, Singapore, will be qualified in the NXP Manchester UK Fab.

For the types in package SOT23 the bond wire material will be changed from gold (Au) to copper (Cu) and a new mold compound and lead frame supplier will be introduced.

Reliability qualification and full electrical characterization over temperature will be performed. No change on thermal behavior or mechanical dimensions. Electrical parameters will remain unchanged (in specification and with the same distribution), except for parameter Rg.

No impact to the products' functionality anticipated.

For details please see the SQP enclosed to this PCN.

#### Why do we Plan this Change

Since Global Foundries stopped the production of TrenchMOS wafer types, they will be transferred to the NXP inhouse wafer fab.

NXP continues to introduce copper wire for plastic SMD packages, aligning with world technology standards. Copper wire shows enhanced mechanical properties.

#### Identification of Affected Products

Changed products can be identified by date code after implementation.

## Product Availability

### Sample Information

Samples are available upon request

Samples can be ordered now and will be shipped after FPCN issue date.

### Production

Planned first shipment 23-May-2017

## Impact

no impact to the product's functionality anticipated.

No impact to the products' functionality anticipated.

### Data Sheet Revision

A new datasheet will be issued

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

The Self Qualification Report will be ready on 08-Feb-2017.

The Final PCN is planned to be issued on: 08-Feb-2017.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 08-Jan-2017.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
PMXB360ENEAZ	934067475147	PMXB360ENEA	small signal MOSFET	SOT1215	DFN1010D-3	RFS	BL GA DISCRETES
PMV130ENEAR	934067623215	PMV130ENEA	small signal MOSFET	SOT23	TO-236AB	RFS	BL GA DISCRETES